



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-10-30
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH1003SB-TR	HWDP*I38K11F	A	994X	2017-10-30
Amount	UoM	Unit type	ST ECOPACK Grade	
320.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	Die back side metal _ Leadframe meta	75
Lead	3.24	Soft solder	10138

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HWDP#138K11F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.575	mg	supplier	die	Silicon (Si)	7440-21-3		3.451	mg	965315	10784
				supplier	metallization	Aluminium (Al)	7429-90-5		0.043	mg	12028	134
				supplier	Passivation	Silicon Oxide	7631-86-9		0.014	mg	3916	44
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	559	6
				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	1399	16
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	6713	75
				supplier	polymer die coating	Propimide	proprietary		0.036	mg	10070	113
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	995198	512973
Leadframe	Copper & its alloys	164.944	mg	supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	2001	1031
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1444
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	3.244	mg	954960	10138
Soft solder	Solder	3.397	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.085	mg	25022	266
				supplier	solder	Tin (Sn)	7440-31-5		0.068	mg	20018	213
				supplier	wire	Aluminium (Al)	7429-90-5		0.739	mg	1000000	2309
Bonding wires	Other inorganic materials	0.739	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.739	mg	1000000	2309
				supplier	mold compound	Silica, vitreous	60676-86-0		131.304	mg	897498	410325
Encapsulation	Other Organic Materials	146.300	mg	supplier	mold compound	Epoxy resin	25068-38-6		10.241	mg	70000	32003
				supplier	mold compound	Phenol resin	29690-82-2		4.389	mg	30000	13716
				supplier	mold compound	carbon black	1333-86-4		0.366	mg	2502	1144
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266